Universitatea Tehnică din Cluj-Napoca
Facultatea de Electronică, Telecomunicaţii şi Tehnologia Informaţiei
Departamentul de Electronică Aplicată
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LISTA
lucrărilor ştiinţifice în domeniul disciplinelor din postul didactic

A – Teza de doctorat

„Lifetime investigations of capacitors under thermal and electrical stress – Investigatii privind durata de viață a condensatoarelor solicitate electric și termic”
Conducător științific : Prof. dr. ing.Pitică Dan
Domeniul Inginerie Electronică și Telecomunicații
Universitatea Tehnică din Cluj-Napoca
Susţinere publică: 09. 11. 2012

B – Cărţi şi capitole în cărţi publicate în ultimii 10 ani

CĂRŢI

1. **Rajmond JÁNÓ**, Gabriel CHINDRIȘ, *Hardware and Software Testing Principles - Hands-on Training Guide*, Editura Mediamira, Cluj-Napoca, 2017, ISBN: 978-973-713-345-8
2. **Rajmond JÁNÓ**, Adelina Ioana ILIEȘ, *Applied Informatics*, Editura UTPress, Cluj-Napoca, 2024, ISBN: 978-606-737-734-7

C – Lucrări indexate ISI/BDI publicate în ultimii 10 ani

c1) Articole / studii publicate în reviste de specialitate de circulaţie internaţională recunoscute (cotate ISI)

c2) Studii publicate la conferinţe indexate în baze de date internaţionale de referinţă în domeniul ..... (DBLP, ACM, IEEE, SCOPUS)[1]

1. Vlad, T., Pitica, D., Man, L., **Rajmond, J.**, *Optimized methods for theoretical and practical training*, 35th International Spring Seminar on Electronics Technology (ISSE), ISBN 978-1-4673-2241-6, pp. 459-464
2. **Rajmond, J.**, Fodor, A., *Thermal management of embedded devices*, 36th International Spring Seminar on Electronics Technology (ISSE), 2013, ISSN 2161-2528, pp. 30-34

[1] indexate în:
[IEEE] - IEEE Xplore (http://ieeexplore.ieee.org/Xplore/guesthome.jsp)
[ACM] - ACM portal (http://portal.acm.org)
[DBLP] - (http://www.informatik.uni-trier.de)
[SCOPUS] - (http://www.scopus.com)

3. Fodor Alexandra, **Jánó Rajmond**, *Thermal Modelling of IC Packages*, Proceedings of the 18th International Symposium for Design and Technology in Electronic Packaging (SIITME), 2013, pp. 149-152
4. **Jano Rajmond**, Gabriel Chindris, *Intelligent Human Interface Device*, Novice Insights in Electronics, 2010, Cluj-Napoca, Romania
5. O. Gui, T. M. Pătărău, **R. Jano**, Th. Mureşan, O.M. Gui, *Virtual Instrumentation and Data Acquisition in Scientific Investigation of Artworks from the National Cultural Heritage*, IEEE 15th International Symposium for Design and Technology în Packaging (SIITME), 2009, Gyor, Hungary
6. O. Gui, T. M. Pătărău, **R. Jánó**, Th. Mureşan, O.M. Gui, *Aspecte referitoare la instrumentaţia virtuală şi achiziţia de date în investigarea ştiinţifică a operelor de artă din patrimoniul cultural*, *Conferinţa internaţională MATCONS 2009 – Materie şi materiale în/pentru restaurarea – conservarea patrimoniului*, 15-19 septembrie, Craiova, România.
7. **Jano R**., T. M. Pătărău, O. Gui, Th. Mureşan, D. Ienei, O. M. Gui, *Application of Virtual Instrumentation Technology in Scientific Investigation of Artworks From The National Cultural Heritage*, Proc. of the 6th National Conference of Virtual Instrumentation, CNIV 2009, 25 May, Braşov, Edit. BREN, Bucureşti, pp.24-28.
8. O. Gui, T.M. Pătărău, **Jano R**., Th. Mureşan, D. Ienei, O.M. Gui, Interdisciplinary Curricula Development (I): Application of Virtual Instrumentation Technology in Scientific Investigation of Artworks from the Cultural Heritage, Proc. of the 4th
9. Fodor, Alexandra; **Jano, Rajmond**; Pitica, Dan, *Thermal Influences on IC Packages During Manual Soldering Process*, 37th International Spring Seminar on Electronics Technology (ISSE) - Advances in Electronic System Integration MAY 07-11, 2014 Dresden, GERMANY, pp. 54 - 57, ISBN 978-1-4799-4455-2
10. **Rajmond, J.**, Fodor, A., *Thermal management of embedded devices*, 36th International Spring Seminar on Electronics Technology (ISSE), 2013, ISSN 2161-2528, pp. 30-34
11. **Jano, Rajmond**; Fodor, Alexandra, *Soldering Profile Optimization for Through-Hole and Surface Mounted Ceramic Capacitors*, 37th International Spring Seminar on Electronics Technology (ISSE) - Advances in Electronic System Integration MAY 07-11, 2014 Dresden, GERMANY, pp. 174 - 179, ISBN 978-1-4799-4455-2
12. Alexandra, Fodor; **Rajmond, Jano**; Dan, Pitica, *Flow Simulations for Component Spacing Optimization on PCB Boards*, 20th IEEE International Symposium on Design and Technology in Electronic Packaging (SIITME) Location: Bucharest, ROMANIA Date: OCT 23-26, 2014, ISBN:978-1-4799-6962-3
13. Fodor, Alexandra; **Jano, Rajmond**; Pitica, Dan, *Component placement optimizations on PCBs for improved thermal behaviour*; Electronics Technology (ISSE), 2015 38th International Spring Seminar on, 6-10 May 2015, pp. 114 – 117
14. **Rajmond, Jano**; Alexandra, Fodor, *Educational tool for capacitor lifetime prediction*, Electronics Technology (ISSE), 2015 38th International Spring Seminar on, 6-10 May 2015, pp. 500 – 504
15. Alexandra, Fodor; Gabriel, Chindris; **Rajmond, Jano**; Dan, Pitica; *Guidelines on thermal management solutions for modern packaging technologies - a review*,' Design and Technology in Electronic Packaging (SIITME), 2015 IEEE 21st International Symposium for, Brasov, 2015, pp. 41-44.
16. **R. Jánó**, A. Fodor and A. I. Ilieş, "Simulation and educational tool for fault modelling in logic circuits," 2016 39th International Spring Seminar on Electronics Technology (ISSE), Pilsen, 2016, pp. 476-479.

17. A. I. Ilieş, **R. Jánó** and G. Chindriş, "Thermal management of System-on-Chip devices used in satellite systems under low temperature conditions," 2016 39th International Spring Seminar on Electronics Technology (ISSE), Pilsen, 2016, pp. 91-96.
18. A. Fodor, G. Chindris, D. Pitica and **R. Jano**, "Task allocation for thermal optimization in multicore systems," 2016 IEEE 12th International Conference on Intelligent Computer Communication and Processing (ICCP), Cluj-Napoca, 2016, pp. 349-352.
19. A. Miclăuş, **R. Jánó** and G. Chindriş, "Implementation of a car model for indirect tire pressure monitoring system," 2016 39th International Spring Seminar on Electronics Technology (ISSE), Pilsen, 2016, pp. 316-321.
20. A. Fodor, **R. Jánó**, G. Chindris and D. Pitica, "Thermal via placement for high-power applications," 2017 IEEE 23rd International Symposium for Design and Technology in Electronic Packaging (SIITME), Constanta, Romania, 2017, pp. 223-226
21. **R. Jánó**, A. Fodor and A. I. Ilieş, "Compact SD card backup system for use in photography," 2017 IEEE 23rd International Symposium for Design and Technology in Electronic Packaging (SIITME), Constanta, Romania, 2017, pp. 145-148
22. A. Fodor, **R. Jano** and D. Pitica, "Investigations of thermal influences on clock speed of embedded devices," 2017 40th International Spring Seminar on Electronics Technology (ISSE), Sofia, 2017, pp. 1-4
23. **R. Jánó** and A. Fodor, "Optimizations for Heat Dissipation Strategies on PC Motherboards," 2019 42nd International Spring Seminar on Electronics Technology (ISSE), Wroclaw, Poland, 2019, pp. 1-5.
24. A. Fodor, G. Chindris, **R. Jano** and D. Pitica, "Thermal Modelling and Simulation Techniques for Multicore Processors," 2019 42nd International Spring Seminar on Electronics Technology (ISSE), Wroclaw, Poland, 2019, pp. 1-5.
25. A. Fodor and **R. Jánó**, "Thermal Characterization of Passive Cooling Techniques for High-Power Component Clusters," 2018 IEEE 24th International Symposium for Design and Technology in Electronic Packaging (SIITME), Iasi, 2018, pp. 209-212.
26. A. Fodor, **R. Jánó** and R. T. Fizeșan, "Characterization of the V-Model Approach in Thermal Design Process," 2019 IEEE 25th International Symposium for Design and Technology in Electronic Packaging (SIITME), 2019, pp. 367-370, doi: 10.1109/SIITME47687.2019.8990783.
27. **R. Jánó** and A. Fodor, "Optimizations for Heat Dissipation Strategies on PC Motherboards," 2019 42nd International Spring Seminar on Electronics Technology (ISSE), 2019, pp. 1-5, doi: 10.1109/ISSE.2019.8810263.
28. A. Fodor, G. Chindris, **R. Jano** and D. Pitica, "Thermal Modelling and Simulation Techniques for Multicore Processors," 2019 42nd International Spring Seminar on Electronics Technology (ISSE), 2019, pp. 1-5, doi: 10.1109/ISSE.2019.8810200.
29. **R. Jánó** and A. Fodor, "Cooling Techniques for M.2 to PCI(e) Adapters," 2020 IEEE 26th International Symposium for Design and Technology in Electronic Packaging (SIITME), 2020, pp. 382-385, doi: 10.1109/SIITME50350.2020.9292191.
30. A. I. Ilieș, G. Chindriș, D. Pitică and **R. Jano**, "Experimental Estimation of the State of Health of Lithium-ion Batteries under Different Conditions," 2021 IEEE 27th International Symposium for Design and Technology in Electronic Packaging (SIITME), 2021, pp. 165-168, doi: 10.1109/SIITME53254.2021.9663419.
31. Rajmond Jánó;Adelina Ioana Ilieș;Alexandra Fodor, „Thermal Simulations for 18650 Li-Ion Batteries", 2022 IEEE 28th International Symposium for Design and Technology in Electronic Packaging (SIITME), 2022
32. R. Jánó, A. I. Ilieș and E. M. Șteţco, "Advancing Forest Conservation: IoT Devices for Monitoring the Wellbeing of Ecosystems," *2024 IEEE 30th International Symposium for*

Design and Technology in Electronic Packaging (SIITME), Sibiu, Romania, 2024, pp. 50-54, doi: 10.1109/SIITME63973.2024.10814863.

33. R. Jánó, A. I. Ilieș and A. Fodor, "Optimizations of the Packaging of Li-Ion Battery Packs for Increasing Preconditioning Efficiency," *2024 IEEE 30th International Symposium for Design and Technology in Electronic Packaging (SIITME)*, Sibiu, Romania, 2024, pp. 40-44, doi: 10.1109/SIITME63973.2024.10814805.
34. R. Jánó, A. I. Ilieş, E. M. Ştefco and C. Corches, "IoT Devices for Monitoring and Analysing Air Quality in Urban Environments," *2024 IEEE 30th International Symposium for Design and Technology in Electronic Packaging (SIITME)*, Sibiu, Romania, 2024, pp. 45-49, doi: 10.1109/SIITME63973.2024.10814899.
35. A. I. Ilies and R. Jánó, "Characterizing Thermal Properties of 18650 Lithium-Ion Battery Cells: Experimental Approaches to Thermal Conductivity and Specific Heat Capacity Measurements," *2024 IEEE 30th International Symposium for Design and Technology in Electronic Packaging (SIITME)*, Sibiu, Romania, 2024, pp. 163-167, doi: 10.1109/SIITME63973.2024.10814772.
36. A. Fodor, A. C. Davidas, A. Grama, E. M. Stetco, A. I. Ilies and R. Jano, "Thermal Simulations and Characterization of High-Power LED Boards," *2024 IEEE 30th International Symposium for Design and Technology in Electronic Packaging (SIITME)*, Sibiu, Romania, 2024, pp. 324-327, doi: 10.1109/SIITME63973.2024.10814810.

D – Lucrări publicate în ultimii 10 anii în reviste şi volume de conferinţe cu referenţi (neindexate)

E – Brevete obţinute pentru întreaga activitate

F – Contracte de cercetare (2020-2025)

1. Activitati de cercetare in cadrul proiectelor AQxx-3, QCU3 si DQxx, Nr. proiect: CS 10C la N-CC-CDI 33619/09.12.2020
2. Optimizarea metodelor de preconditionare pentru maximizarea performantei bateriilor Li-Ion, Nr. proiect: 16/01-07-2024

Data

19.01.2025

Semnătura